

30 April 2003

09/762,582

L Number	Hits	Search Text	DB	Time stamp
-	0	762582.apn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 11:23
-	9	((("5116430") or ("3716462") or ("3930963"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 13:53
-	1	jp-51149131-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 12:13
-	2	4163705.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 12:13
-	7	((("5849171") or ("4430173") or ("5433840"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 09:43
-	2657	204/198,212,232,242,273,275.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 13:55
-	773	204/224r.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 13:55
-	3270	204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 13:55
-	35	(204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.) and electroless and (electrolytic or electroplating) and robot	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:04
-	58753	204/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:04
-	55	204/\$.ccls. and electroless and (electrolytic or electroplating) and robot	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:04
-	20	(204/\$.ccls. and electroless and (electrolytic or electroplating) and robot) not ((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.) and electroless and (electrolytic or electroplating) and robot)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:14
-	2	6080291.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:07

-	813	204/\$.ccls. and (robot or robotic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:14
-	78	(204/\$.ccls. and (robot or robotic)) and electroless	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:15
-	81	204/\$.ccls. and electroless and (robot or robotic or (transfer adj unit) or (transfer adj device) or (transfer adj arm))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:16
-	26	(204/\$.ccls. and electroless and (robot or robotic or (transfer adj unit) or (transfer adj device) or (transfer adj arm))) not (204/\$.ccls. and electroless and (electrolytic or electroplating) and robot) not ((204/\$.ccls. and electroless and (electrolytic or electroplating) and robot) not ((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.) and electroless and (electrolytic or electroplating) and robot))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:17
-	26	(204/\$.ccls. and electroless and (robot or robotic or (transfer adj unit) or (transfer adj device) or (transfer adj arm))) not (204/\$.ccls. and electroless and (electrolytic or electroplating) and robot) not ((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.) and electroless and (electrolytic or electroplating) and robot)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:33
-	2	6197181.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:21
-	2	jp-56158424-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:34
-	1	1982-04830E.NRAN.	DERWENT	2003/04/29 14:33
-	2	jp-05311496-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:35
-	2	jp-07193214-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:37
-	1	1995-217803.NRAN.	DERWENT	2003/04/29 14:37
-	2	jp-02000341-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:39
-	1	1990-047945.NRAN.	DERWENT	2003/04/29 14:39

-	2	jp-56161221-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:42
-	1	jp-51149131-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:43
-	1	1976-75692X.NRAN.	DERWENT	2003/04/29 14:42
-	2	jp-03146698-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:44
-	2	jp-05098500-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:45
-	2	jp-62235499-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:46
-	2	jp-63026400-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:50
-	1	1997wo-??22733.ap.prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:51
-	0	wo-22733-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:52
-	0	wo-00022733-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:52
-	0	wo-97022733-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 14:52
-	58753	204/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 15:10
-	708	204/\$.ccls. and (electroless and (electrolytic or electroplating or electroplate))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 15:11
-	82	(204/\$.ccls. and (electroless and (electrolytic or electroplating or electroplate))) and (robot or robotic or ((transfer or conveyance or conveyor) adj (means! or unit or device or system or arm)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 15:12

-	160054	205/\$.ccls. or 427/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 15:47
-	14963	(205/\$.ccls. or 427/\$.ccls.) and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 15:48
-	759	((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or wafer)) and electroless and (electroplating or electroplated or electroplate or electrolytic or electrochemically)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 15:49
-	54	((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or wafer)) and (electroless near2 (tank or bath)) and ((electroplating or electroplated or electroplate or electrolytic or electrochemically) near2 (tank or bath))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 15:49
-	60	((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or wafer)) and (electroless near2 (tank or bath or chamber)) and ((electroplating or electroplated or electroplate or electrolytic or electrochemically) near2 (tank or bath or chamber))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 15:54
-	7	((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or wafer)) and (electroless near2 (tank or bath or chamber)) and ((electroplating or electroplated or electroplate or electrolytic or electrochemically) near2 (tank or bath or chamber))) and (robot or robotic or ((transfer or conveyor or conveyance) near (arm or unit or device or means!)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 15:51
-	29	((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or wafer)) and (electroless near2 (tank or bath or chamber)) and ((electroplating or electroplated or electroplate or electrolytic or electrochemically) near2 (tank or bath or chamber))) and ((copper adj sulfate) or "Cuso.sub.4")	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/29 15:55
-	8	("5500315" or ("5310580" or ("5389496" or ("5139818"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 08:52
-	0	electroless and ((copper adj sulfate) or "cuso.sub.4") and ((chlorine or chloride) adj ions) and (sulfuric adj acid)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 08:54
-	1896	electroless and ((copper adj sulfate) or "cuso.sub.4")	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 08:54
-	1019	(electroless and ((copper adj sulfate) or "cuso.sub.4")) and (sulfuric adj acid)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 08:54

-	220	((electroless and ((copper adj sulfate) or "cuso.sub.4")) and (sulfuric adj acid)) and (((polyethylene or polypropylene) adj glycol) or peg! or ppg!)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 08:55
-	52	((electroless and ((copper adj sulfate) or "cuso.sub.4")) and (sulfuric adj acid)) and (((polyethylene or polypropylene) adj glycol) or peg! or ppg!)) and sulfur and nitrogen	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 08:55
-	51	((electroless and ((copper adj sulfate) or "cuso.sub.4")) and (sulfuric adj acid)) and (((polyethylene or polypropylene) adj glycol) or peg! or ppg!)) and sulfur and nitrogen) and (chlorine or chloride)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 09:06
-	0	uk-1222969-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 09:07
-	1	gb-1222969-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 09:11
-	59	(204/\$.ccls. or 205/\$.ccls.) and bubble and (pressure near (module or modulation or modulating or pulse or pulsating or pulsed or pulsing or pulsated or varied or variable or cyclical))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 10:01
-	8	(204/\$.ccls. or 205/\$.ccls.) and (bubble with (pressure near (module or modulation or modulating or pulse or pulsating or pulsed or pulsing or pulsated or varied or variable or cyclical)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 10:09
-	111	(204/\$.ccls. or 205/\$.ccls.) and ((bubble or gas) same (pressure near (module or modulation or modulating or pulse or pulsating or pulsed or pulsing or pulsated or varied or variable or cyclical)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 10:20
-	102	(204/\$.ccls. or 205/\$.ccls.) and ((bubble or gas) same (pressure near (modulate or modulation or modulating or pulse or pulsating or pulsed or pulsing or pulsated or varied or variable or cyclical)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 13:38
-	21529	(204/\$.ccls. or 205/\$.ccls.) and (semiconductor or wafer or microelectronic or (integrated adj circuit) or (circuit board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 10:19
-	2051	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor or wafer or microelectronic or (integrated adj circuit) or (circuit board))) and bubble	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 10:19
-	241	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor or wafer or microelectronic or (integrated adj circuit) or (circuit board))) and (bubble with pressure)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 10:20

-	69	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor or wafer or microelectronic or (integrated adj circuit) or (circuit board))) and ((bubble or gas) same (pressure near (modulate or modulation or modulating or pulse or pulsating or pulsed or pulsing or pulsated or varied or variable or cyclical)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 10:21
-	2	5865894.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 13:41
-	83136	204/\$.ccls. or 205/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 13:41
-	18	(204/\$.ccls. or 205/\$.ccls.) and (semiconductor) and (bubbles with (sonic or ultrasonic or megasonic))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 13:45
-	2	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor) and (bubbles with (sonic or ultrasonic or megasonic))) and (hermetically or sealed)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 13:45
-	10914	204/198,212,232,242,273,275.1.ccls. 204/224r.ccls. 205/88,98,122,123,125,148,157,183,184,187,261,291.ccls. 427/96,98,443.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 14:07
-	1933	(204/198,212,232,242,273,275.1.ccls. 204/224r.ccls. 205/88,98,122,123,125,148,157,183,184,187,261,291.ccls. 427/96,98,443.1.ccls.) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 14:07
-	506	((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls. 205/88,98,122,123,125,148,157,183,184,187,261,291.ccls. 427/96,98,443.1.ccls.) and semiconductor) and	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 14:07
-	135	((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls. 205/88,98,122,123,125,148,157,183,184,187,261,291.ccls. 427/96,98,443.1.ccls.) and semiconductor) and electroless) and ((copper adj (sulfate or sulphate)) or	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 14:08
-	61	((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls. 205/88,98,122,123,125,148,157,183,184,187,261,291.ccls. 427/96,98,443.1.ccls.) and semiconductor) and electroless) and ((copper adj (sulfate or sulphate)) or	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 14:11
-	18	((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls. 205/88,98,122,123,125,148,157,183,184,187,261,291.ccls. 427/96,98,443.1.ccls.) and semiconductor) and electroless) and ((copper adj (sulfate or sulphate)) or	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 14:12
-	2	((204/198,212,232,242,273,275.1.ccls. 204/224r.ccls. 205/88,98,122,123,125,148,157,183,184,187,261,291.ccls. 427/96,98,443.1.ccls.) and semiconductor) and electroless) and ((copper adj (sulfate or sulphate)) or	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/30 14:12

"cuso-sub.4") and hermetically